

Thick Film, Resistor Array



The CRA04P thick film resistor array is constructed on a high grade ceramic body with concave terminations. A small package enables the design of high density circuits. The single component reduces board space, component counts and assembly costs.

FEATURES



- · Concave terminal array with square corners
- Wide ohmic range: 1R0 to 1M0
- 8 terminal package with isolated resistors
- Lead (Pb)-free solder contacts on NI barrier layer
- Pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes
- Compatible with "Restriction of the use of Hazardous Substances" (RoHS) directive 2002/95/EC (issue 2004)

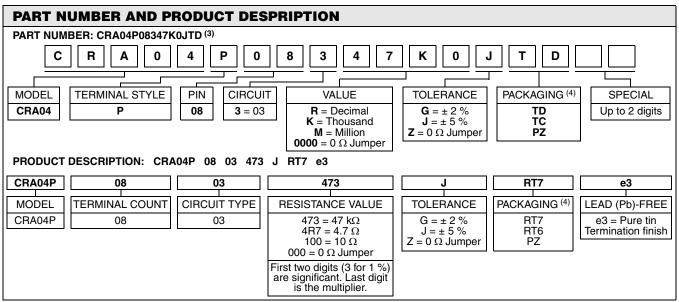
STANE	TANDARD ELECTRICAL SPECIFICATIONS								
MODEL	CIRCUIT	POWER RATING P _{70 °C} W	LIMITING ELEMENT VOLTAGE MAX. V≅	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	$\begin{array}{c} \textbf{RESISTANCE} \\ \textbf{RANGE} \\ \Omega \end{array}$	E-SERIES		
		0.063	50	± 100	± 2	10R - 1M0	24		
CRA04P	03	0.003	50	± 200	± 5	1R0 - 1M0	24		
		Zero-Ohm-Resistor: $R_{\text{max.}} = 50 \text{ m}\Omega$, $I_{\text{max.}} = 1 \text{ A}$							

TECHNICAL SPECIFICATIONS					
PARAMETER	UNIT	CRA04P			
Rated Dissipation at 70 °C (2)	W per element	0.063			
Limiting Element Voltage (1)	V≅	50			
Insulation Voltage (1 min)	V _{dc/ac peak}	100			
Category Temperature Range	°C	- 55 to + 155			
Insulation Resistance	Ω	> 10 ⁹			

Notes

Rated voltage: $\sqrt{P \times R}$

The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.



Notes

(3) Preferred way for ordering products is by use of the PART NUMBER
 (4) Please refer to the table PACKAGING, see next page

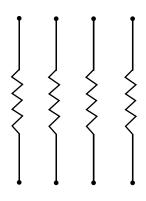
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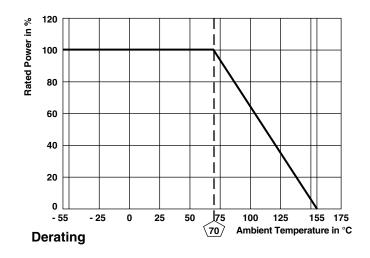


PACKAGI	ACKAGING						
					PACKING CODE		
MODEL	TAPE WIDTH	DIAMETER	PITCH	PIECES/REEL	P	APER TAPE	
					PART NUMBER	PRODUCT DESCRIPTION	
		180 mm/7"	2 mm	10 000	TD	RT7	
CRA04P	8 mm	330 mm/13"	2 mm	20 000	TC	RT6	
		330 mm/13"	2 mm	50 000	PZ	PZ	

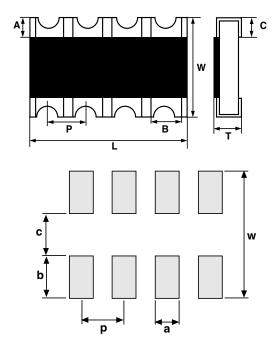
CIRCUIT

03 Circuit





DIMENSIONS



PIN NO#	DIMENSIONS [in millimeters]								
	L	Α	В	С	P _{NOM}	Т	w		
8	2.00	0.20	0.32	0.25	0.50	0.35	1.00		
TOL.	± 0.10	± 0.10	± 0.10	± 0.10	-	± 0.10	± 0.10		

SOLDER PAD DIMENSIONS [in millimeters]						
	c w p a b					
WAVE	0.5	1.5	0.5	0.32	0.5	

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EN 60115-1						
TEST		REQUIREMENTS PERMISSIBLE CHANGE (\(\triangle R/R\)\(^{(1)}\) STABILITY CLASS 2 OR BETTER				
(clause)	CONDITIONS OF TEST					
	Stability for product types:	40 0 to 4 MO	1 Ω to 1 MΩ			
	CRA04P	10 Ω to 1 M Ω				
Resistance (4.5)	-	± 2 %	± 5 %			
Temperature coefficient (4.8.4.2)	20/- 55/20 °C and 20/125/20 °C	± 100 ppm/K	± 200 ppm/K			
Overload (4.13)	$U = 2.5 \times (P_{70} \times R)^{1/2}$ $\leq 2 \times U_{\text{max}}; 0.5 \text{ s}$	± (0.5 % R + 0.05 Ω)				
Solderability (4.17.5) (2)	Aging 4 h at 155 °C, dryheat solder bath method; 235 °C; 2 s visual examination	Good tinning (≥ 95 % covered) no visible damage				
Resistance to soldering heat (4.18.2)	Solder bath method; (260 ± 5) °C; (10 ± 1) s	± (0.5 % R + 0.05 Ω)				
Rapid change of temperature (4.19)	30 min at LCT = - 55 °C; 30 min at UCT = 125 °C; 5 cycles	± (0.5 % R + 0.05 Ω)				
Damp heat, steady state (4.24)	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (2 % R + 0.1 Ω)				
Climatic sequence (4.23)	16 h at UCT = 125 °C; 1 cycle at 55 °C; 2 h at LCT = -55 °C; 1 h/1 kPa at 15 °C to 35 °C; 5 cycles at 55 °C U = (P ₇₀ x R) ^{1/2} U = U _{max} ; whichever is less severe	± (2 % R + 0.1 Ω)				
Endurance at 70 °C (4.25.1)	$U = (P_{70} \times R)^{1/2}$ $U = U_{\text{max}}$; whichever is less severe 1.5 h ON; 0.5 h OFF; 70 °C; 1000 h	± (2 % R + 0.1 Ω)				
Extended endurance (4.25.1.8)	Duration extended to 8000 h	± (4 % R + 0.1 Ω)				
Endurance at upper category temperature (4.25.3)	UCT = 125 °C; 1000 h	± (2 % R + 0.1 Ω)				

Notes

(1) Figures are given for a single element

(2) Solderability is specified for 2 years after production or requalification. Permitted storage time is 20 years

APPLICABLE SPECIFICATIONS

EN 60115-1 Generic Specification
 EN 140400 Sectional Specification
 EN 140401-802 Detail Specification

IEC 60068-2-X
 Variety of environmental test procedures

• EIA 481 Packaging of SMD components



Vishay

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